

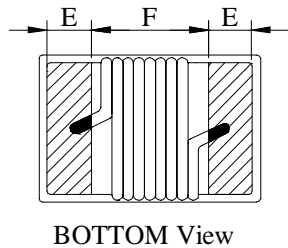
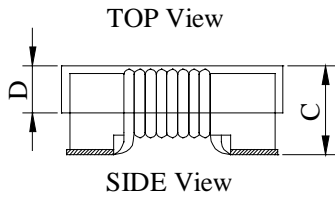
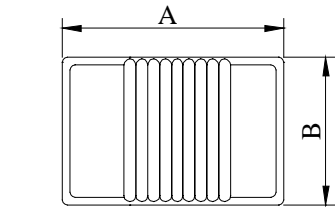
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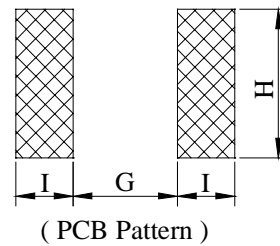
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PROD. NAME	WOUND CHIP INDUCTOR	ABC'S DWG NO.	SW1005□□□□L□
		ABC'S ITEM NO.	

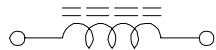
. CONFIGURATION & DIMENSIONS :



- A : 1.00 ± 0.1 m/m
- B : 0.55 ± 0.1 m/m
- C : 0.50 ± 0.1 m/m
- D : 0.30 m/m
- E : 0.20 m/m
- F : 0.50 m/m
- G : 0.40 m/m
- H : 0.40 m/m
- I : 0.50 m/m

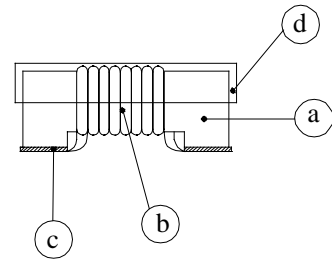


. SCHEMATIC DIAGRAM :

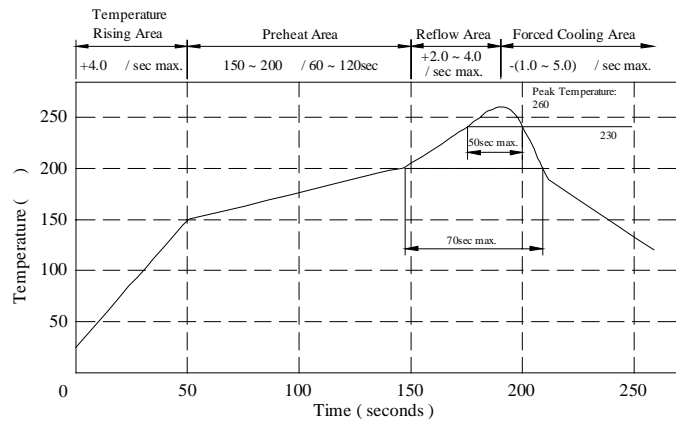


. MATERIALS :

- a . Core : Ceramic
- b . WIRE : Enamelled copper wire (class H)
- c . Terminal : Mo / Mn + Ni + Au
- d . Encapsulate : Epoxy
- e . Remark : Lead content 200ppm max.
include ceramic



Peak Temp : 260 max.
 Max time above 230 : 50sec max.
 Max time above 200 : 70sec max.



. GENERAL SPECIFICATION :

- a . Temp rise : 15 max
- b . Rated current : Current cause inductance drop within 10% max.
- c . Stopage temp. : -40 ----+125
- d . Operating temp. : -40 ----+125

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PROD. NAME	WOUND CHIP INDUCTOR	ABC'S DWG NO.	SW1005□□□□L□
		ABC'S ITEM NO.	

. ELECTRICAL CHARACTERISTICS :

DWG No.	Inductance (nH)	Q min.	L / Q Test Freq. (MHz)	SRF (MHz) min.	RDC (Ω) max.	IDC (mA) max.
SW10051N0DL□	1.0 ± 0.3	13	250	6000	0.045	1360
SW10052N0DL□	2.0 ± 0.3	16	250	6000	0.070	1040
SW10052N2DL□	2.2 ± 0.3	18	250	6000	0.070	960
SW10053N3DL□	3.3 ± 0.3	20	250	6000	0.066	840
SW10053N6DL□	3.6 ± 0.3	20	250	6000	0.066	840
SW10053N9DL□	3.9 ± 0.3	20	250	5800	0.066	840
SW10055N1JL□	5.1 ± 5%	23	250	5800	0.083	800
SW10055N6JL□	5.6 ± 5%	23	250	5800	0.083	760
SW10056N2JL□	6.2 ± 5%	23	250	5800	0.083	760
SW10057N5JL□	7.5 ± 5%	25	250	5800	0.104	680
SW10058N2JL□	8.2 ± 5%	25	250	4400	0.104	680
SW10059N0JL□	9.0 ± 5%	25	250	4160	0.104	680
SW100510NJL□	10.0 ± 5%	23	250	3900	0.195	480
SW100511NJL□	11.0 ± 5%	26	250	3680	0.120	640
SW100512NJL□	12.0 ± 5%	26	250	3600	0.120	640
SW100515NJL□	15.0 ± 5%	26	250	3280	0.172	560
SW100519NJL□	19.0 ± 5%	26	250	3040	0.202	480
SW100523NJL□	23.0 ± 5%	26	250	2720	0.214	400
SW100527NJL□	27.0 ± 5%	26	250	2480	0.298	400
SW100536NJL□	36.0 ± 5%	26	250	2320	0.403	320
SW100540NJL□	40.0 ± 5%	26	250	2240	0.438	320
SW100547NJL□	47.0 ± 5%	26	200	2100	0.830	150

1). □ : Packaging Information... **A**: Bulk **B**: Taping Reel

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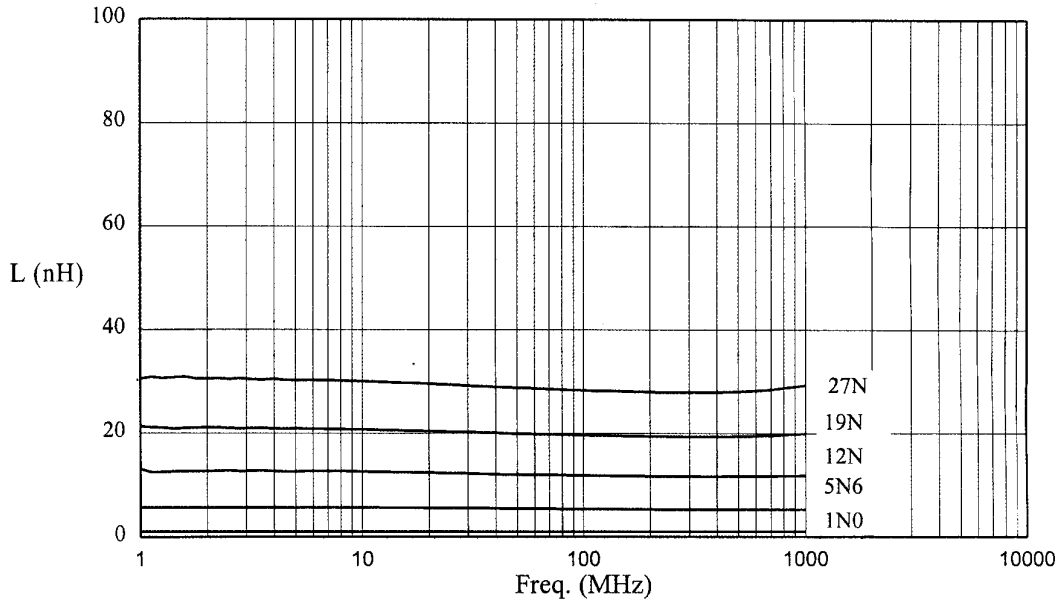
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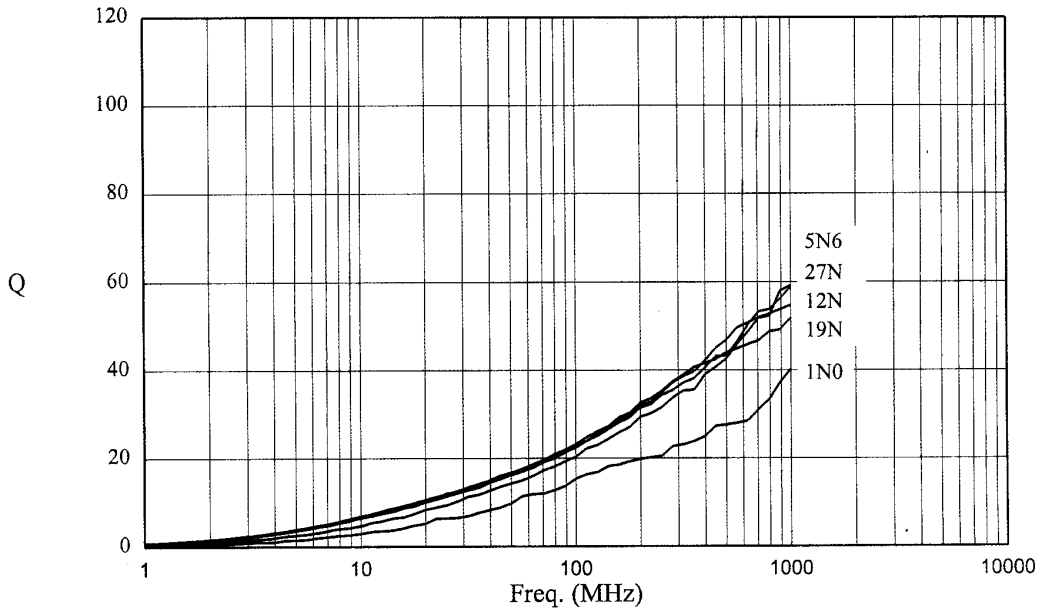
PROD. NAME	WOUND CHIP INDUCTOR	ABC'S DWG NO. ABC'S ITEM NO.	SW1005□□□□L□
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CURVE :

L vs Freq Plot



Q vs Freq Plot



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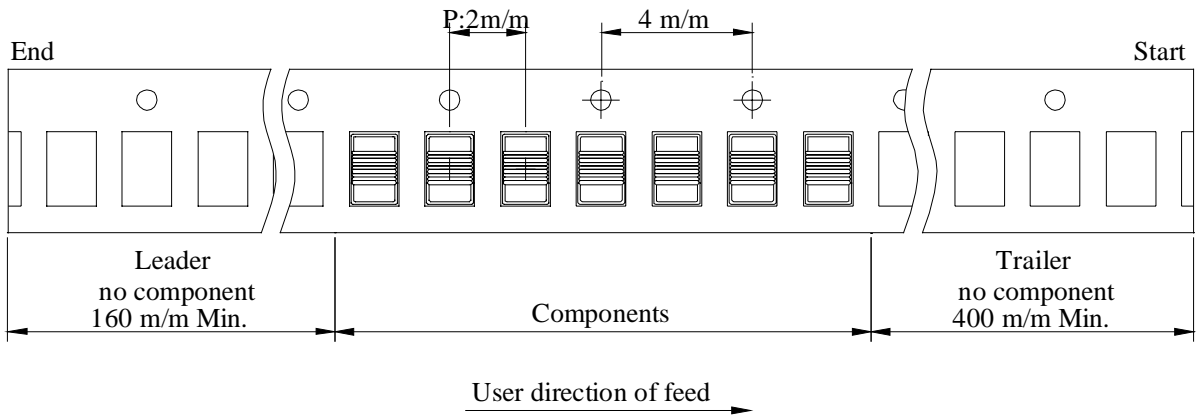
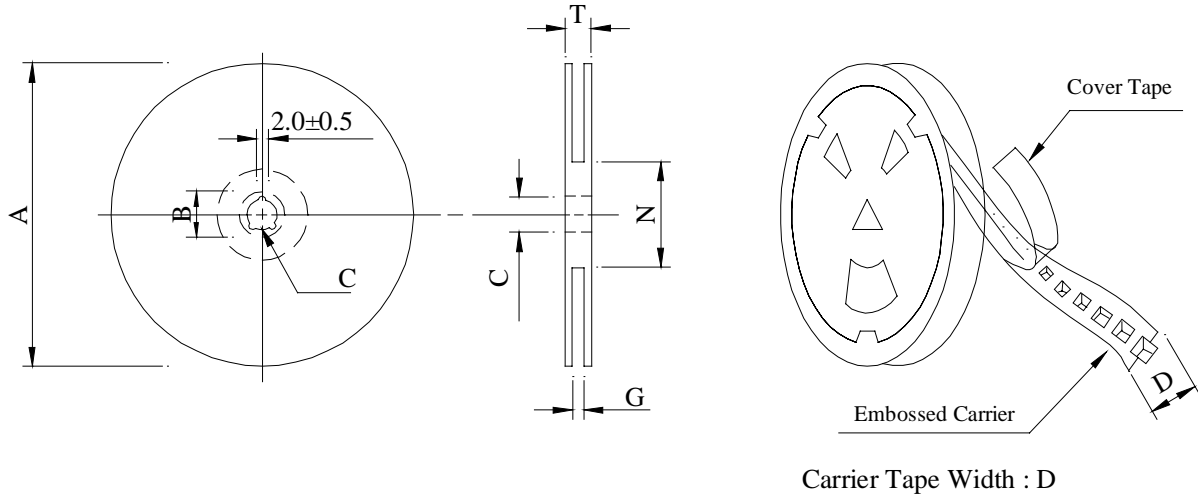
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PROD. NAME	WOUND CHIP INDUCTOR	ABC'S DWG NO.	SW1005□□□□L□
		ABC'S ITEM NO.	

. PACKAGING INFORMATION :

(1) Configuration



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(2) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
SW1005	10,000	100	07 - 08	500,000	5.50	41 x 39 x 22

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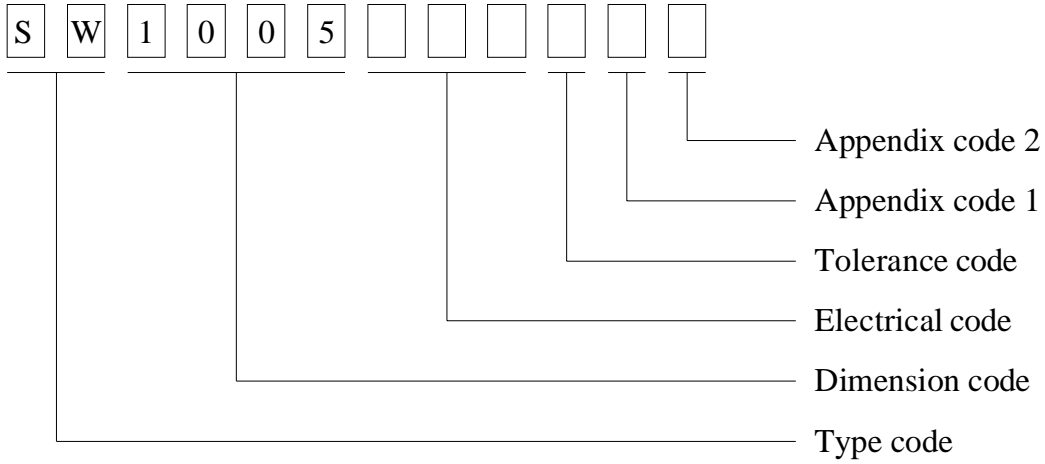
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PROD. NAME	WOUND CHIP INDUCTOR	ABC'S DWG NO.	SW1005□□□□L□
		ABC'S ITEM NO.	

. DWG EXPRESSION :



Appendix code 1 : S : Standard products

A K , M R , T Z : Special products

L : Standard Lead Free products

1 ~ 9 : Special Lead Free products

Appendix code 2 :

Code	Inner package	Inner package Q'TY	Remark
A	Empty	Empty	
B	T / R (Reel package)	10000 pcs	

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PROD. NAME	WOUND CHIP INDUCTOR	ABC'S DWG NO.	SW1005□□□□□□
		ABC'S ITEM NO.	

. RELIABILITY TEST :

Test items	Specifications	Test conditions / Test methods
<i>ELECTRICAL PERFORMANCE TEST</i>		
L	Refer to standard electrical characteristic list	HP-4291A With HP-16193 Test fixture .
Q		HP-4291A With HP-16193 Test fixture.
SRF		HP-8753E
RDC		HP-4338B
Rated current IDC		Applied the current to coils the inductance change shall be less than 10% to initial value and temperature rise shall not be more than 20
Temperature rise test	20 max.	1.Applied the allowed DC current for 10 minutes. 2.Temperature measure by digital surface thermometer .
Over load test	After test , Inductors shall be no evidence of electrical and mechanical damage	Applied 2 times of rated allowed DC current to inductor for a period of five minutes .
Withstanding voltage test	After test , Inductors shall be no evidence of electrical and mechanical damage	500VAC between inductor terminals and center of case for a maximum 1 minute.
Insulation resistance test	1000 MΩ min.	100 VDC between inductor terminals and center case.
<i>MECHANICAL PERFORMANCE TEST</i>		
Vibration test (Low frequency)	1.There shall be no case deformation or change in appearance. 2.Inductance shall not change more than ±5% 3.Q shall not change more than±10%	1.Amplitude : 1.5 m/m 2.Frequency : 10-55-10Hz/min. 3.Direction : X,Y,Z 4.Duration : 2HRS/X,Y,Z
Vibration test (Low frequency)		Inductors shall be dropped 10 times from a height of 1m onto 3cm wooden board .
Resistance to soldering heat		Inductors shall be reflowed onto a P.C. board using solder paste. Solder process shall be 230 for 20±2 seconds and 260 for 5±2 seconds
Solderability test		The metalized area must have 90% min. solder coverage

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PROD. NAME	WOUND CHIP INDUCTOR	ABC'S DWG NO. ABC'S ITEM NO.	SW1005□□□□L□																												
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 25%; padding: 5px;">Component adhesion (Push test)</td> <td style="width: 30%; padding: 5px;">20N : 2012 , 2520 , 3225 10N : 1608 5N : 1005</td> <td style="width: 45%; padding: 5px;">The device shall be reflow soldered (230±5 for 10 seconds) to a tinned copper substrate. A dynamometer force gauge shall be applied to the side of the component . The device must withstand the minimum force indicated at left without a failure of the termination to board attachment.</td> </tr> <tr> <td colspan="3" style="text-align: center; padding: 5px;"><i>CLIMATIC TEST</i></td> </tr> <tr> <td style="padding: 5px;">Temperature characteristic</td> <td rowspan="5" style="padding: 5px;">1. There shall be no case deformation or change in appearance. 2. Inductance shall not change more than ±5% 3. Q shall not change more than ±10%</td> <td style="padding: 5px;">-40 ~125</td> </tr> <tr> <td style="padding: 5px;">Humidity test</td> <td style="padding: 5px;">Temp. : 50±2 R.H. : 90~95 % Time. : 96±2 hours</td> </tr> <tr> <td style="padding: 5px;">Low temperature storage</td> <td style="padding: 5px;">Temp. : -40±2 Time. : 48±2 hours</td> </tr> <tr> <td style="padding: 5px;">Thermal shock test</td> <td style="padding: 5px;">-40 for 30 minutes. +125 for 30 minutes. Total : 10 cycles</td> </tr> <tr> <td style="padding: 5px;">High temperature storage</td> <td style="padding: 5px;">Temp. : 125±2 Time. : 48±2 hours</td> </tr> <tr> <td colspan="3" style="padding: 5px;">Note : Inductors are to be tested after 1 hour at room temperature.</td> </tr> <tr> <td colspan="3" style="text-align: center; padding: 5px;"><i>LIFE TEST</i></td> </tr> <tr> <td style="padding: 5px;">High temperature load life test</td> <td rowspan="2" style="padding: 5px;">Inductors shall not have a shorted or open winding.</td> <td style="padding: 5px;">1.Temp : 85±2 2.Time : 1000±12 hours 3.Load : Allowed DC current</td> </tr> <tr> <td style="padding: 5px;">Humidity load life</td> <td style="padding: 5px;">1.Temp : 40±2 2.R.H. : 90-95% 3.Time : 1000±12 hours 4. Load : Allowed DC current</td> </tr> </table>				Component adhesion (Push test)	20N : 2012 , 2520 , 3225 10N : 1608 5N : 1005	The device shall be reflow soldered (230±5 for 10 seconds) to a tinned copper substrate. A dynamometer force gauge shall be applied to the side of the component . The device must withstand the minimum force indicated at left without a failure of the termination to board attachment.	<i>CLIMATIC TEST</i>			Temperature characteristic	1. There shall be no case deformation or change in appearance. 2. Inductance shall not change more than ±5% 3. Q shall not change more than ±10%	-40 ~125	Humidity test	Temp. : 50±2 R.H. : 90~95 % Time. : 96±2 hours	Low temperature storage	Temp. : -40±2 Time. : 48±2 hours	Thermal shock test	-40 for 30 minutes. +125 for 30 minutes. Total : 10 cycles	High temperature storage	Temp. : 125±2 Time. : 48±2 hours	Note : Inductors are to be tested after 1 hour at room temperature.			<i>LIFE TEST</i>			High temperature load life test	Inductors shall not have a shorted or open winding.	1.Temp : 85±2 2.Time : 1000±12 hours 3.Load : Allowed DC current	Humidity load life	1.Temp : 40±2 2.R.H. : 90-95% 3.Time : 1000±12 hours 4. Load : Allowed DC current
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PROD. NAME	WOUND CHIP INDUCTOR	ABC'S DWG NO. ABC'S ITEM NO.	SW1005□□□□L□
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. UL CARD :

OBMW2 August 27, 1999
Magnet Wire-Component

ELEKTRISOLA (MALAYSIA) SDN BHD E143312
IALAN DAMN SATU IANDA BAIK 28750 BENTONG, PAHANG
DARUL MAKMUR MALAYSIA

Mtl Dsg	Mark Dsg	Coating Type		ANSI Typ	Temp Class
		BC	OC		
Estersol 160	E180	Polyesterimide (solderable)	—	MW-77	180
Amldester 200	A200	Polyesterimide	—	MW-74	200
Polysol-N 155	PN155	Polyurethane	Nylon	MW-80, MW-28	155, 100
Polysol 155	P155	Polyurethane	—	MW-79, MW-79	155, 130
Polysol 155g	Pg155	Polyurethane	—	MW-79	130
Polysol 155p	Pp155.Gp155	Polyurethane	—	MW-79	155
Polysol 160	P160	Polyurethane	—	MW-79	155
Polysol 180	P180	Polyurethane	—	MW-79	155
Polysol 170	P170 or G170	Polyurethane	—	MW-79	156
Polysol-N 180	PN180	Polyurethane	Nylon	—	180

Marking : Company name/material designation or marked designation and factory identification on package ok reel

See General Information preceding These Recognitions
For use only in equipment where the acceptability of the combination is determined by Underwriters Laboratories Inc.

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